SCES338E - SEPTEMBER 2000 - REVISED APRIL 2005

- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 7 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

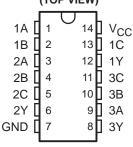
description/ordering information

These triple 3-input positive-NAND gates are designed for 2-V to 5.5-V $\rm V_{CC}$ operation.

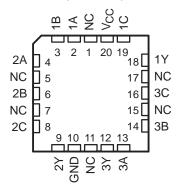
The 'LV10A devices perform the Boolean function $Y = \overline{A \cdot B \cdot C}$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

These devices are fully specified for partial-power-down applications using $I_{\rm off}$. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

SN54LV10A . . . J OR W PACKAGE SN74LV10A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



SN54LV10A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	0010 D	Tube of 50	SN74LV10AD	11/404	
	SOIC – D	Reel of 2500	SN74LV10ADR	LV10A	
	SOP – NS	Reel of 2000	SN74LV10ANSR	74LV10A	
	SSOP – DB	Reel of 2000	SN74LV10ADBR	LV10A	
-40°C to 85°C		Tube of 90	SN74LV10APW		
	TSSOP - PW	Reel of 2000	SN74LV10APWR	LV10A	
		Reel of 250	SN74LV10APWT		
	TVSOP – DGV	Reel of 2000	SN74LV10ADGVR	LV10A	
	CDIP – J	Tube of 25	SNJ54LV10AJ	SNJ54LV10AJ	
−55°C to 125°C	CFP – W	Tube of 150	SNJ54LV10AW	SNJ54LV10AW	
	LCCC - FK	Tube of 55	SNJ54LV10AFK	SNJ54LV10AFK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



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FUNCTION TABLE (each gate)

	INPUTS	OUTPUT	
Α	В	С	Y
Н	Н	Н	L
L	X	Χ	Н
Х	L	Χ	Н
Х	Χ	L	Н

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54L\	/10A	SN74L	UNIT	
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
V	High level in put valte as	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} × 0.7		V _{CC} ×0.7		V
VIH	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		l v
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
V	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V	$CC \times 0.3$	٧	CC×0.3	V
V_{IL}	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	V	$CC \times 0.3$	٧	CC×0.3	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} × 0.3		V	CC×0.3	
VI	Input voltage		0,0	5.5	0	5.5	V
VO	Output voltage		0	VCC	0	VCC	V
		V _{CC} = 2 V	Q.	-50		-50	μΑ
la	High-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		-2	
Іон	nign-ievei output current	$V_{CC} = 3 V \text{ to } 3.6 V$		-6		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12	
		$V_{CC} = 2 V$		50		50	μΑ
	Low lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6		6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		200	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 V \text{ to } 3.6 V$		100		100	ns/V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		20	
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		1	SN54LV10A	SN74LV10A		
PARAMETER	TEST CONDITIONS	VCC	MIN TYP MAX	MIN TYP MAX	UNIT	
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1	V _{CC} -0.1		
.,	$I_{OH} = -2 \text{ mA}$	2.3 V	2	2	.,	
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48	2.48	V	
	I _{OH} = -12 mA	4.5 V	3.8	3.8		
	I _{OL} = 50 μA	2 V to 5.5 V	0.1	0.1		
V	I _{OL} = 2 mA	2.3 V	0.4	0.4	V	
VOL	I _{OL} = 6 mA	3 V	0.44	0.44	V	
	I _{OL} = 12 mA	4.5 V	0.55	0.55		
lį	V _I = 5.5 V or GND	0 to 5.5 V	±1	±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	20	20	μΑ	
l _{off}	V_I or $V_O = 0$ to 5.5 V	0	5	5	μΑ	
Ci	V _I = V _{CC} or GND	3.3 V	1.9	1.9	pF	

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T _A = 25°C			SN54LV10A	SN74LV10A		LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
^t pd	A, B, or C	Υ	C _L = 15 pF		7.1*	13*	1* 15.5*	1	15.5	ns
t _{pd}	A, B, or C	Y	C _L = 50 pF		10.3	17.1	1 20.5	1	20.5	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T _A = 25°C			SN54LV10A	SN74LV10A		LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
^t pd	A, B, or C	Υ	C _L = 15 pF		5.2*	8.4*	1* 10*	1	10	ns
t _{pd}	A, B, or C	Y	$C_L = 50 pF$		7.4	11.9	1 13.5	1	13.5	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	4 = 25°C	;	SN54LV10A	SN74L	.V10A	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
^t pd	A, B, or C	Υ	C _L = 15 pF		3.9*	5.9*	1 7*	1	7	ns
t _{pd}	A, B, or C	Υ	C _L = 50 pF		5.4	7.9	1 9	1	9	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 5)

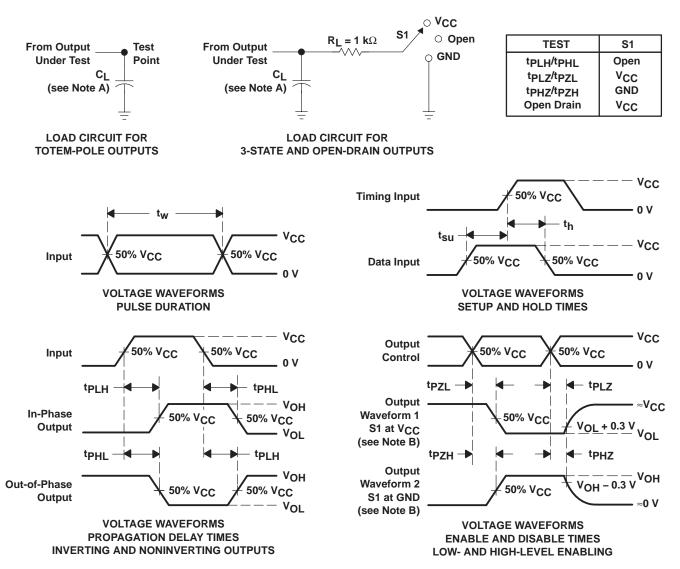
	DADAMETED	SN	SN74LV10A			
	PARAMETER	MIN	TYP	MAX	UNIT	
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V	
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		0	-0.8	V	
VOH(V)	Quiet output, minimum dynamic VOH		3.2		V	
VIH(D)	High-level dynamic input voltage	2.31			V	
V _{IL(D)}	Low-level dynamic input voltage			0.99	V	

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

ĺ		PARAMETER	TEST CO	NDITIONS	VCC	TYP	UNIT
ľ	0 .	Davisa discinsting consistence	O. 50 F	4 40 MH-	3.3 V	14	٠.
l	C _{pd}	Power dissipation capacitance	$C_L = 50 pF$,	f = 10 MHz	5 V	16.7	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV10AD	ACTIVE	SOIC	D	14	50	RoHS & Green	(6) NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A	
SIN/4LV TUAD	ACTIVE	3010	D	14	50	Kuns & Green	MIPDAU	Level- 1-200C-OINLIIVI	-40 10 65	LVIUA	Samples
SN74LV10ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A	Samples
SN74LV10ADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A	Samples
SN74LV10ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV10A	Samples
SN74LV10APW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A	Samples
SN74LV10APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A	Samples
SN74LV10APWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





Α0	<u> </u>
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

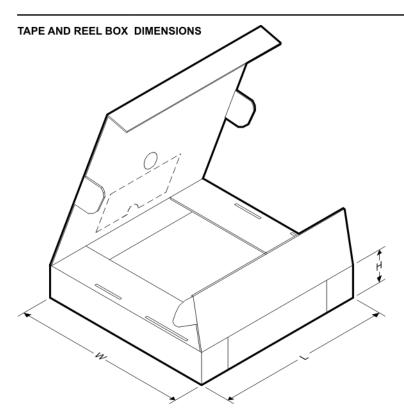
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV10ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV10ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV10APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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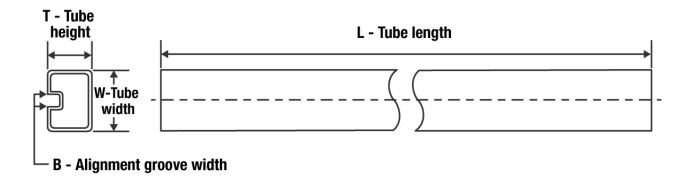
*All dimensions are nominal

7 til dillionorio di o momina								
Device	Package Type	Package Drawing Pins		SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LV10ADR	SOIC	D	14	2500	853.0	449.0	35.0	
SN74LV10ANSR	SO	NS	14	2000	853.0	449.0	35.0	
SN74LV10APWR	TSSOP	PW	14	2000	853.0	449.0	35.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LV10AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LV10APW	PW	TSSOP	14	90	530	10.2	3600	3.5

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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